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Part Number:

0739427000

Status:

Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 144 Circuits

Documents:

3D Model

Packaging Specification PK-70873-0818 (PDF)

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73942

Application

Backplane

Comments

Solder Tail, Solder Tail

Component Type

PCB Header

Overview

HDM Backplane Connector System

Product Name

HDM

UPC

800754802895

Physical

Circuits (Loaded)

144

Circuits (maximum)

144

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Net Weight

6.273/g

Number of Columns

24

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length

3.50mm

PCB Locator

No

PCB Retention

None

PCB Thickness - Recommended

2.50mm

Packaging Type

Tube

Pitch - Mating Interface

2.00mm

Pitch - Termination Interface

2.00mm

Plating min - Mating

0.762µm

Plating min - Termination

2.540µm

Stackable

Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55° to +105°C

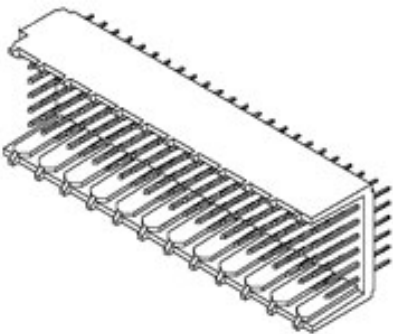
Termination Interface: Style

Through Hole

Electrical

Current - Maximum per Contact

1.0A



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

73942 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Insertion	622005703
Head for 144 Circuits	

Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

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